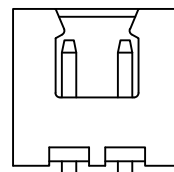
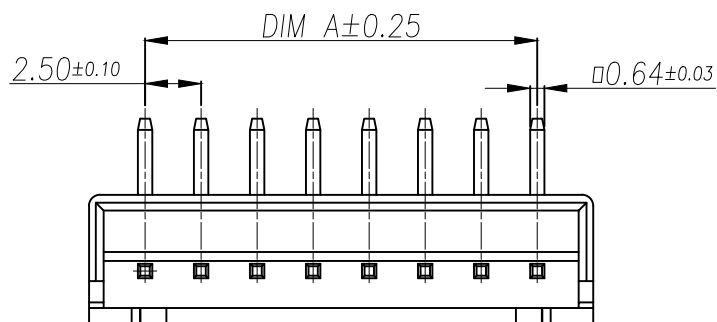


PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE

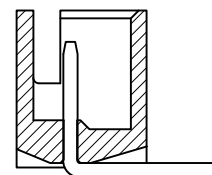
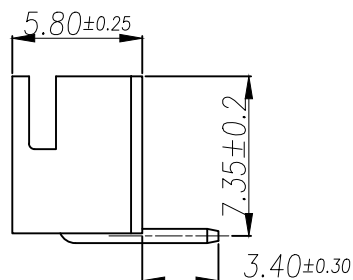
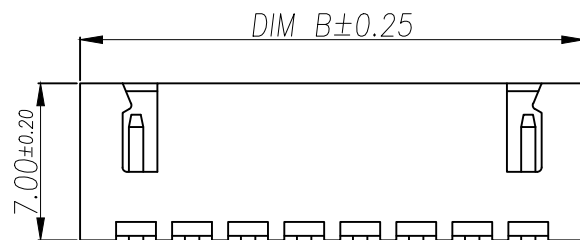
技术要求:

1. 塑件材料: PA66 (UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10\text{m}\Omega$
4. 绝缘电阻: $\geq 1000\text{M}\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 3.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积 $>95\%$ 温度 $235^{\circ}\pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求

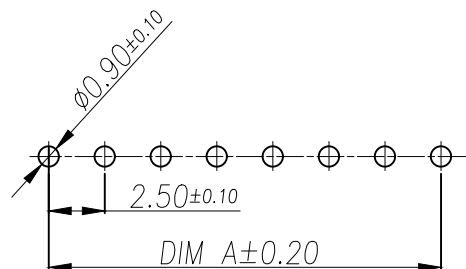
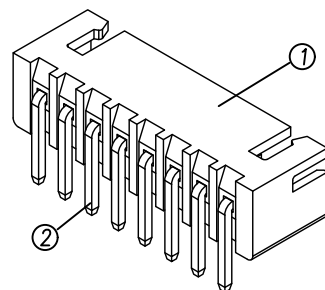
Part No	PIN	A	B
XY-XH-2AW	2	2.5	7.5
XY-XH-3AW	3	5.0	10.0
XY-XH-4AW	4	7.5	12.5
XY-XH-5AW	5	10.0	15.0
XY-XH-6AW	6	12.5	17.5
XY-XH-7AW	7	15.0	20.0
XY-XH-8AW	8	17.5	22.5
XY-XH-9AW	9	20.0	25.0
XY-XH-10AW	10	22.5	27.5
XY-XH-11AW	11	25.0	30.0
XY-XH-12AW	12	27.5	32.5
XY-XH-13AW	13	30.0	35.0
.....	...	...	...
XY-XH-20AW	20	$(20-1)*2.5$	$(20+1)*2.5$



2P



SECTION A-A

SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN, 再镀锡80u"MIN.
1	Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	备注

DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd		
TOLERANCE UNLESS OTHERWISE SPECIFIED		APR. Alex	TITLE: WAFER 2.54mm H7.0mm 90° DIP	
.X±0.35	X.*±5°	CHK. Jack	DWG NO. XY-XH-NAW	
.XX±0.25	.X.*±3°	DRA. Can	PROJ. CUSTOMER DRAWING	
.XXX±0.15	.XX.*±1°	SIZE A4	SCALE 1:1	SHEET 1/1 REV. A